



PRINTED ELECTRONICS AND CARD ASSEMBLY

Discover our capabilities

C2MI offers a wide range of equipment to contribute to your printed electronics or card assembly projects. We have all the necessary toolset to create your circuit: from the ink deposition in various composition, photonic or heat curing to lamination and laser depaneling or drilling, we can build your circuit and assemble any parts that you want to have on it.

From big chips and connectors to 0102 metric components, the placement machines in the state of the art and fully automated line can produce them. Our paste inspection tool will automatically give feedback to the printer and the 3D AOI will be able to assure quality of the final assembly.

Our offering

- Inkjet printing
- Aerosol printing
- Screen printing
- Photonic curing
- Lamination
- Laser drilling and cutting
- Fully automated card assembly
- 3D automated inspection



Paired with our reliability lab, analytical lab, our deep expertise in flip chip and wirebond assembly and all processes to go from a wafer to a package, your next generation product is within reach.

The Centre

C2MI is the largest research and development centre in microelectronic across Canada. Offering state-of-the-art equipment dedicated mainly to advanced packaging, micro-electromechanical systems (MEMS), printed electronics and card assembly, the Centre also welcomes more than 250 scientists.

“Collaboration and Synergy among our partners promote rapid commercialization of advanced prototypes.”



MiQro Innovation
Collaborative Centre

45 boulevard de l'Aéroport
Bromont, QC, Canada, J2L 1S8
450-534-8000
www.c2mi.ca

